

USB7216

Hardware Design Checklist

1.0 INTRODUCTION

This document provides a hardware design checklist for the Microchip USB7216. These checklist items should be followed when utilizing the USB7216 in a new design. A summary of these items is provided in Section 9.0, "Hardware Checklist Summary," on page 31. Detailed information on these subjects can be found in the corresponding section:

- · Section 2.0, "General Considerations"
- Section 3.0, "Power and Bypass Capacitance"
- · Section 3.0, "Power and Bypass Capacitance"
- · Section 4.0, "USB Signals and Connections"
- · Section 5.0, "Clock Circuit"
- · Section 6.0, "Power and Startup"
- Section 7.0, "External SPI Memory"
- · Section 8.0, "Configuration, Straps, and Miscellaneous Interfaces"

2.0 GENERAL CONSIDERATIONS

2.1 Required References

At a minimum, the circuit designer should have the following documents on hand:

- · USB7216 Data Sheet
- USB7216 Errata
- AN26.2 Implementation Guidelines for Microchip USB 2.0 and USB 3.1 Gen 1 Hub Devices
- · AN2932 USB-to-GPIO Bridging with Microchip USB72xx Hubs
- AN2935 Configuration of USB7202/USB7206/USB725x
- AN3135 USB-to-I²S Bridging with Microchip Hubs
- AN3240 USB-to-l²C Bridging with Microchip USB720x and USB725x Hubs
- · USB 2.0 Specification
- USB 3.1 Specification

2.2 Pin Check

Check the pinout of the part against the data sheet. Ensure that all pins match the data sheet and are configured as inputs, outputs, or bidirectional for error checking.

2.3 Ground

- The ground pin, GND, should be connected to the solid ground plane on the board.
- It is recommended that all ground connections be tied together to the same ground plane. Separate ground planes are not recommended.

2.4 USB-IF Compliant USB Connectors

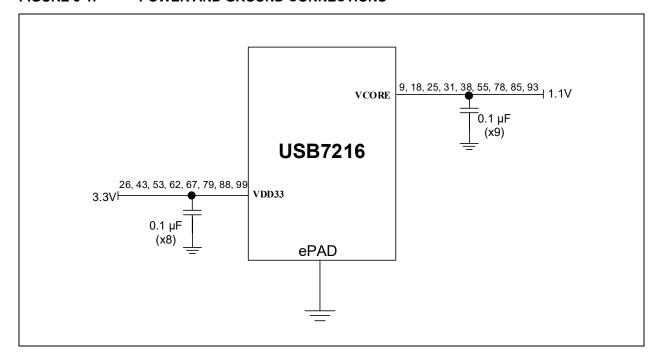
 USB-IF certified USB connectors with a valid Test ID (TID) are required for all USB products to be compliant and pass USB-IF product certification.

3.0 POWER AND BYPASS CAPACITANCE

- The analog supplies (VDD33) require connections to a regulated 3.3V power plane.
 - For USB7216, VDD33 is located on pins 26, 43, 53, 62, 67, 79, 88, and 99.
- Each VDD33 pin each should include a 0.1 μF capacitor to decouple the device. The capacitor size should be SMD_0603 or smaller.
- The analog supplies (VCORE) require connections to a regulated 1.15V power plane.
 - For USB7216, VCORE is located on pins 9, 18, 25, 31, 38, 55, 78, 85, and 93.
- Each VCORE pin each should include a 0.1 μF capacitor to decouple the device. The capacitor physical size should be SMD_0603 or smaller.

The power and ground connections are shown in Figure 3-1.

FIGURE 3-1: POWER AND GROUND CONNECTIONS



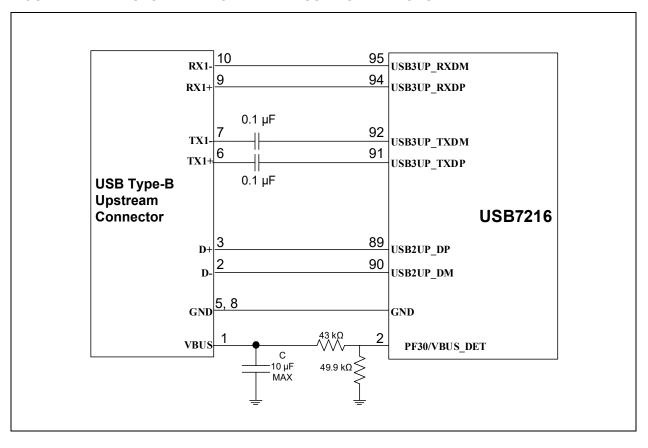
4.0 USB SIGNALS AND CONNECTIONS

4.1 Upstream Port USB Signals

- USB2UP_DP (pin 89): This pin is the positive (+) signal of the upstream USB2.0 differential pair. All necessary
 USB terminations and resistors are included in the IC. This pin can connect directly to the D+/DP¹ pin of a USB
 connector.
- USB2UP_DM (pin 90): This pin is the negative (-) signal of the upstream USB2.0 differential pair. All necessary
 USB terminations and resistors are included in the IC. This pin can connect directly to the D-/DM¹ pin of a USB
 connector.
- USB3UP_TXDP (pin 91): This pin is the positive (+) signal of the upstream USB3.1 'Side A' transmitter (TX) differential pair. All necessary USB terminations and resistors are included in the IC. This pin requires a series of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX+ (or TX-)² pin of the USB connector.
- USB3UP_TXDM (pin 92): This pin is the negative (-) signal of the upstream USB3.1 'Side A' TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin requires a series of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX- (or TX+)² pin of the USB connector.
- USB3UP_RXDP (pin 94): This pin is the positive (+) signal of the upstream USB3.1 'Side A' receiver (RX) differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX+ (or RX-)² pin of the USB connector.
- USB3UP_RXDM (pin 95): This pin is the negative (-) signal of the upstream USB3.1 'Side A' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX- (or RX+)² pin of the USB connector.
 - **Note 1:** The polarity of any of the USB2.0 differential pairs may be inverted either intentionally due to design constraints or to correct a design error using the Microchip PortSwap feature. This feature may be configured via One-Time Programmable (OTP) or SMBus/I²C configuration registers.
 - 2: A standard feature of USB3.1 is automatic polarity detection and correction. The positive and negative pins of the TX lines can be swapped with no adverse effect. Similarly, the positive and negative pins of the RX lines can also be swapped.

For the standard Type-B port connection details, see Figure 4-1.

FIGURE 4-1: UPSTREAM PORT TYPE-B USB CONNECTIONS

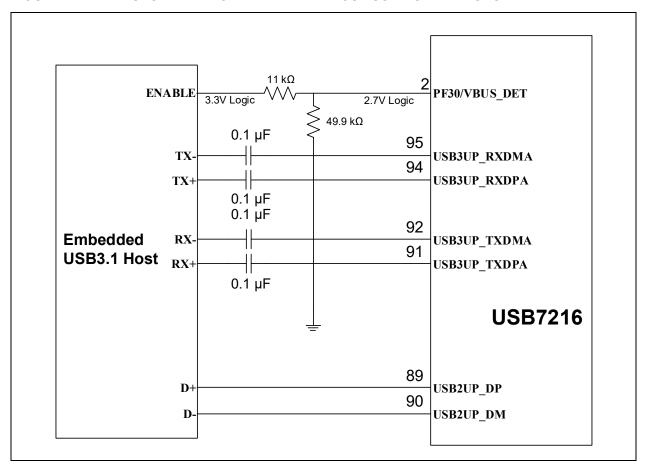


When connecting the upstream port to an embedded USB3.1 host, some pin connections change:

- The VBUS_MON_UP pin may be connected to an Enable output from the host processor. Alternatively, this can be tied to a 3.3V power rail, but a host control is recommended, whether it be through the VBUS_MON_UP pin or the RESET_N pin. In any case, the voltage of the signal must be reduced to 2.7V for input to the USB7216.
- · Series capacitors are needed in both TX and RX USB3 signal pairs with an embedded host.

For an example on how to connect the upstream port to an embedded USB3.1 host, refer to Figure 4-2.

FIGURE 4-2: UPSTREAM PORT EMBEDDED HOST USB CONNECTIONS



4.2 Downstream Port 1

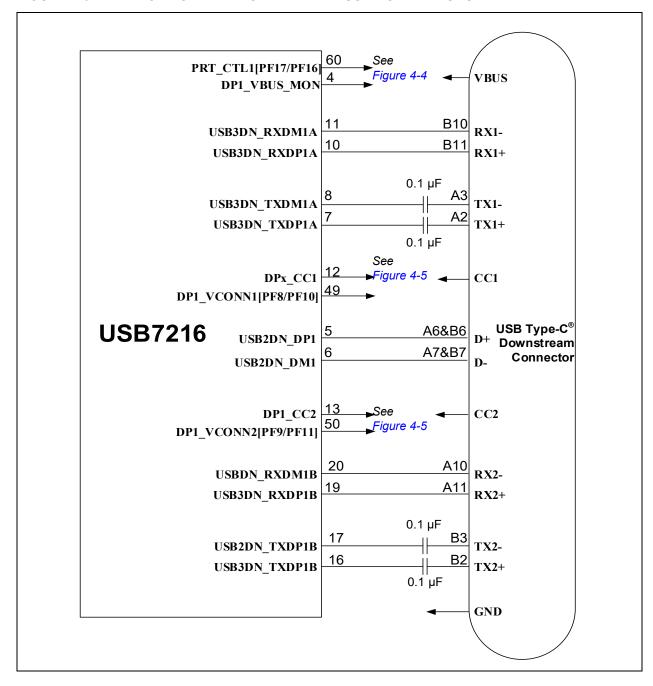
4.2.1 DOWNSTREAM PORT 1 USB SIGNALS

- USB2DN_DP1/USB2DN_DP2 (pin 5/29): This pin is the positive (+) signal of the downstream port USB2.0 differential pair. All necessary USB terminations and resistors are included in the IC. This pin can connect directly to the D+/DP¹ pin of a USB connector.
- USB2DN_DM1/USB2DN_DM2 (pin 6/30): This pin is the negative (-) signal of the downstream port USB2.0 differential pair. All necessary USB terminations and resistors are included in the IC. This pin can connect directly to the D-/DM¹ pin of a USB connector.
- USB3DN_TXDP1A/USB3DN_TXDP2A (pin 7/31): This pin is the positive (+) signal of the downstream port
 USB3.1 'Side A' TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin
 requires a series of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX+ (or
 TX-)² pin of the USB connector.
- USB3DN_TXDM1A/USB3DN_RXDP2A (pin 8/32): This pin is the negative (-) signal of the downstream port
 USB3.1 'Side A' TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin
 requires a series of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX- (or
 TX+)² pin of the USB connector.
- USB3DN_RXDP1A/USB3DN_RXDP2A (pin 10/34): This pin is the positive (+) signal of the downstream port USB3.1 'Side A' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX+ (or RX-)² pin of the USB connector.
- USB3DN_RXDM1A/USB3DN_RXDM2A (pin 11/35): This pin is the negative (-) signal of the downstream port USB3.1 'Side A' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX- (or RX+)² pin of the USB connector.
- USB3DN_TXDP1B/USB3DN_TXDP2B (pin 16/39): This pin is the positive (+) signal of the downstream port
 USB3.1 'Side B' TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin
 requires a series of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX+ (or TX)² pin of the USB connector.
- USB3DN_TXDM1B/USB3DN_TXDM2B (pin 17/40): This pin is the negative (-) signal of the downstream port USB3.1 'Side B' TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin requires a series of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX- (or TX+)² pin of the USB connector.
- USB3DN_RXDP1B/USB3DN_RXDP2B (pin 19/42): This pin is the positive (+) signal of the downstream portUSB3.1 'Side B' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX+ (or RX-)² pin of the USB connector.
- USB3DN_RXDM1B/USB3DN_RXDN2B (pin 20/43): This pin is the negative (-) signal of the downstream port USB3.1 'Side B' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX- (or RX+)² pin of the USB connector.
- DP1_CC1/DP2_CC1 (pin 12/27): This pin is used to detect a USB Type-C[®] connection and insertion orientation. This should connect directly to the CC1 pin of the USB Type-C connector.
- DP1_CC2/DP2_CC2 (pin 13/28): This pin is used to detect a USB Type-C connection and insertion orientation. This should connect directly to the CC2 pin of the USB Type-C connector.
 - **Note 1:** The polarity of any of the USB2.0 differential pairs may be inverted either intentionally due to design constraints or to correct a design error using the Microchip PortSwap feature. This feature may be configured via OTP or SMBus/I²C configuration registers.
 - **2:** A standard feature of USB3.1 is automatic polarity detection and correction. The positive and negative pins of the TX lines can be swapped with no adverse effect. Similarly, the positive and negative pins of the RX lines can also be swapped.

4.2.2 DOWNSTREAM PORT 1 TYPE-C USB SIGNAL CONNECTIONS

For standard Type-C port connection details, refer to Figure 4-3.

FIGURE 4-3: DOWNSTREAM PORT 1 TYPE-C USB CONNECTIONS



When connecting the upstream port to a legacy Type-B connector, some pin connections change:

- · All of the 'Side B' TX and RX pins should be left floating.
- The DP1_CC1 pin should be connected directly to GND through a 5.1 k Ω pull-up resistor.
- The DP1_CC2 pin should be left floating.
- DP1_VCONN1 and DP1_VCONN2 pins should be left floating.

4.2.3 DOWNSTREAM PORT 1 TYPE-C VBUS AND PRT CTLX CONNECTIONS

Port Power Control is required for bus-powered devices and battery charging.

The PRT CTL1 pin is a hybrid input/output (I/O) pin that has the following states:

- PORT OFF: PRT_CTL1 is an output and drives low. The PRT_CTL1 pin only transitions to the PORT ON state through a specific command from the USB host.
- PORT ON: PRT_CTL1 is an input with a weak internal pull-up enabled. The input buffer monitors overcurrent
 events, which are indicated by the port power controller by pulling the PRT_CTL1 line low. Once an overcurrent
 event is detected, the PRT_CTL1 automatically moves to the PORT OFF state until the USB host can be notified
 of the overcurrent event.

When connecting the PRT_CTL1 pin to a port power controller, the signal should be connected to both the Enable and the fault indicator pins of the port power controller. Do not place an external pull-up resistor on the line.

Note: The overcurrent detect debounce parameters are configurable and may be adjusted if required to operate properly with the selected port power controller.

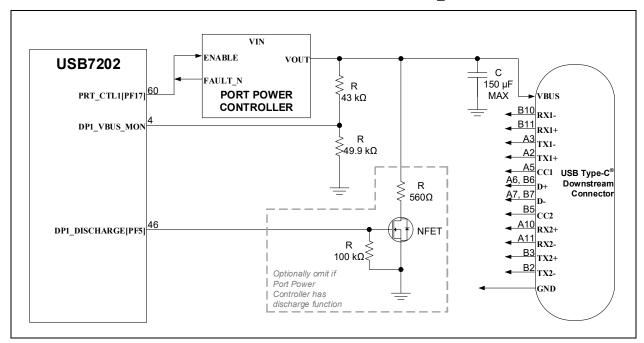
The $DP1_VBUS_MON$ pin is an input with a preconfigured set of comparator banks. These comparator banks are used to monitor the voltage on the VBUS pin to ensure that the voltage is within the correct range while in the VBUS ON and OFF states ('vSafe5V' and 'vSafe0V', respectively). The recommended connection to VBUS is through a resistor divider of $43 \text{ k}\Omega$ over $49.9\text{k}\Omega$. This pin must be connected per this guidance and may not be left floating or unused.

The DP1_DISCHARGE pin is an output that asserts whenever power to VBUS is transitioning from ON to OFF ('vSafe5V' to 'vSafe0V'). This pin can be connected to a transistor that should turn on and short VBUS to GND when this signal asserts to 3.3V. A series resistor in the $400-700\Omega$ range is recommended to limit the current through the transistor and to add discharge slew rate controllability. When discharging the VBUS pin, the voltage must reach the vSafe0V voltage window within the discharge time as defined in the USB Type-C Specification (see the latest revision for the most up-to-date timing and voltage requirements).

Some port power controllers have an automatic discharge function when they are shut off. In that case, the DP1_DIS-CHARGE pin may be left floating.

A typical Type-C implementation is shown in Figure 4-4.

FIGURE 4-4: DOWNSTREAM PORT 1 TYPE-C VBUS AND PRT_CTL CONNECTIONS



Note: The implementation as shown in Figure 4-4 assumes that the port power controller has an active-high Enable input, and an active-low, open drain style fault indicator. External polarity inversion through buffers or FETs may be required if the port power controller has different I/O characteristics.

4.2.4 DOWNSTREAM PORT 1 CC1 AND CC2 CONNECTIONS

If connecting downstream port 1 to a Type-A port, see Figure 4-6.

If connecting downstream port 1 to an embedded USB device, see Figure 4-5.

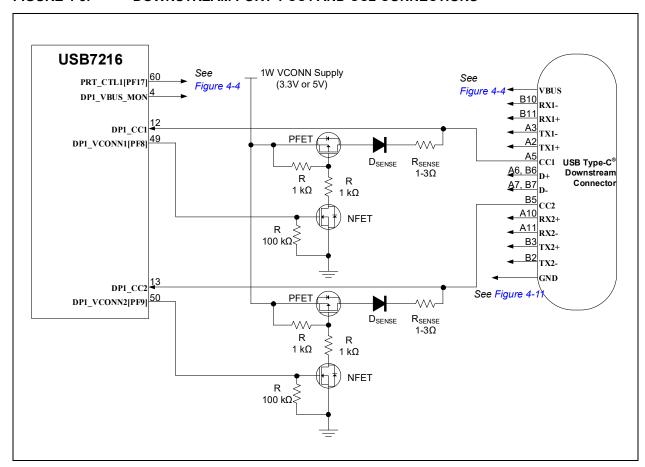
DP1_CC1 and **DP1_CC2** of downstream port 1 of USB7216 are designed to connect directly to the respective CC1 and CC2 pins of the Type-C connector.

DP1_VCONN1 and DP1_VCONN2 of downstream port 1 of USB7216 are active high control signals that assert when the VCONN should be supplied to an active or electronically marked cable or to a VCONN powered accessory. The VCONN supply for a standard Type-C application must be capable of supplying 1W of VCONN power to each Type-C downstream port. For the VCONN power supply, 5V is recommended though lower voltages are also supported. The recommended arrangement is an NFET to invert the polarity of the control signal, and a PFET pass transistor for the VCONN voltage.

VCONN overcurrent is sensed by voltage drop on the CCx pin. A diode and a low impedance series resistor may be necessary to ensure this voltage drop is achieved when VCONN current draw exceeds the desired overcurrent threshold. The diode and resistor characteristics should be tuned by the system designer to match the exact desired overcurrent setting.

A typical implementation is shown in Figure 4-5.

FIGURE 4-5: DOWNSTREAM PORT 1 CC1 AND CC2 CONNECTIONS



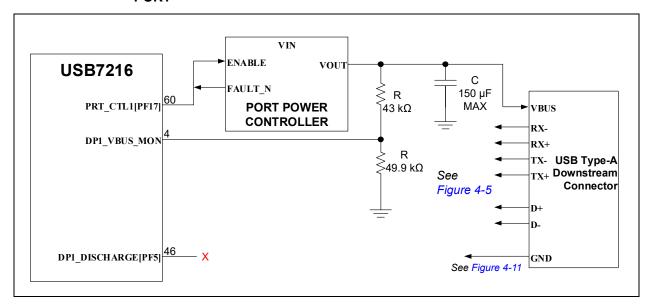
Note: The implementation as shown in Figure 4-5 assumes that the Type-C controller has an active-high Enable input, and the port power controller have an active-low, open drain style fault indicator. External polarity inversion through buffers or FETs may be required if the Type-C controller, port power controller, or both have different I/O characteristics.

4.2.5 DOWNSTREAM PORT 1 TYPE-A VBUS AND PRT_CTL1 CONNECTIONS

When connecting downstream port 1 to a standard Type-A port, the **DP1_VBUS_MON** pin must still be connected in the same manner, but **DP1_DISCHARGE** may be left disconnected, as a standard Type-A port is an 'always on' port that does not require fast discharging.

A typical Type-A implementation is shown in Figure 4-6.

FIGURE 4-6: DOWNSTREAM PORT 1 VBUS AND PRT_CTLX CONNECTIONS FOR TYPE-A PORT

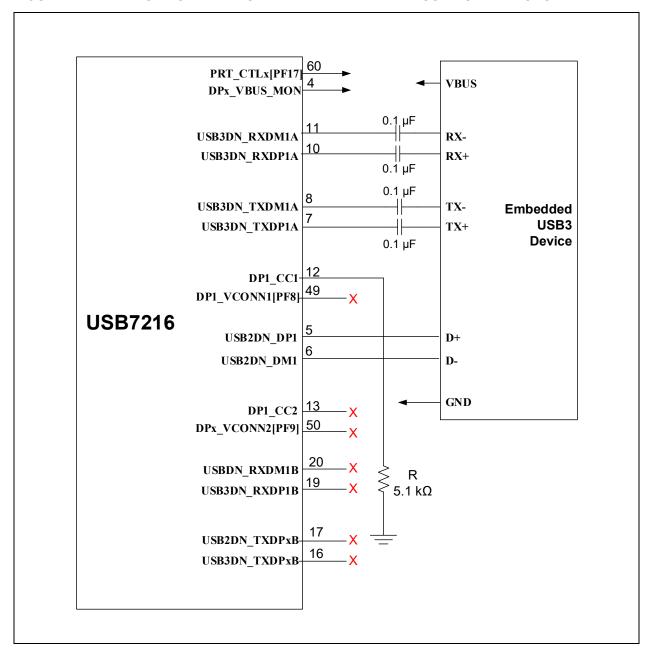


Note: The implementation as shown in Figure 4-6 assumes that the port power controller has an active-high Enable input, and an active-low, open drain style fault indicator. External polarity inversion through buffers or FETs may be required if the port power controller has different I/O characteristics.

4.2.6 DOWNSTREAM PORT 1 EMBEDDED DEVICE CONNECTIONS

For an example on how to connect downstream port 1 to an embedded USB3.1 device, refer to Figure 4-7.

FIGURE 4-7: DOWNSTREAM PORT 1 EMBEDDED DEVICE USB CONNECTIONS



4.3 Downstream Ports 2-6

Ports 2, 3, and 4 are legacy Type-A USB3 ports. Ports 5 and 6 are Type-A USB2 ports that have no USB3 signals.

4.3.1 DOWNSTREAM TYPE-A USB SIGNALS

- USB2DN_DPx (pin 27/34/81/14/42): This pin is the positive (+) signal of the downstream port USB2.0 differential pair. All necessary USB terminations and resistors are included in the IC. This pin can connect directly to the D+/DP¹ pin of a USB connector.
- USB2DN_DMx (pin 28/35/82/15/41): This pin is the negative (-) signal of the downstream port USB2.0 differential pair. All necessary USB terminations and resistors are included in the IC. This pin can connect directly to the D-/ DM¹ pin of a USB connector.
- USB3DN_TXDPx (pin 29/36/83/na/na): This pin is the positive (+) signal of the downstream port USB3.1 'Side A'
 TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin requires a series
 of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX+ (or TX-)² pin of the USB
 connector.
- USB3DN_TXDMx (pin 30/37/84/na/na): This pin is the negative (-) signal of the downstream port USB3.1 'Side A'
 TX differential pair. All necessary USB terminations and resistors are included in the IC. This pin requires a series
 of 0.1 uF decoupling (DC blocking) capacitor before being connected directly to the TX- (or TX+)² pin of the USB
 connector.
- USB3DN_RXDPx (pin 32/39/86/na/na): This pin is the positive (+) signal of the downstream port USB3.1 'Side A' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX+ (or RX-)² pin of the USB connector.
- USB3DN_RXDMx (pin 33/40/87/na/na): This pin is the negative (-) signal of the downstream port USB3.1 'Side A' RX differential pair. All necessary USB terminations and resistors are included in the IC. This pin can be connected directly to the RX- (or RX+)² pin of the USB connector.
 - **Note 1:** The polarity of any of the USB2.0 differential pairs may be inverted either intentionally due to design constraints or to correct a design error using the Microchip PortSwap feature. This feature may be configured via OTP or SMBus/I2C configuration registers.
 - **2:** A standard feature of USB3.1 is automatic polarity detection and correction. The positive and negative pins of the TX lines can be swapped with no adverse effect. Similarly, the positive and negative pins of the RX lines can also be swapped.
- PRT_CTLx and DPx_VBUS_MON can be shorted together and connected directly to the Enable signal of the USB3.1 device, assuming a 3.3V logic level is required by the device. This gives the USB host the ability to reset the device through standard USB protocol.

4.3.2 DOWNSTREAM PORTS 2, 3, AND 4 VBUS AND VBUS_DET AND USB SIGNALS

The PRT_CTLx pin is a hybrid I/O pin that has the following states:

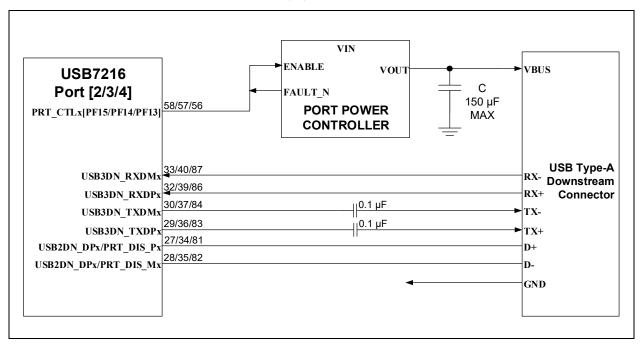
- PORT OFF: PRT_CTLx is an output and drives low. The PRT_CTLx pin only transitions to the PORT ON state through a specific command from the USB host.
- PORT ON: PRT_CTLx is an input with a weak internal pull-up enabled. The input buffer monitors overcurrent events, which are indicated by the port power controller by pulling the PRT_CTLx line low. Once an overcurrent event is detected, the PRT_CTLx automatically moves to the PORT OFF state until the USB host can be notified of the overcurrent event.

When connecting the PRT_CTLx pin to a port power controller, the signal should be connected to both the Enable and the fault indicator pins of the port power controller. Do not place an external pull-up resistor on the line.

Note: The overcurrent detect debounce parameters are configurable and may be adjusted if required to operate properly with the selected port power controller.

A typical Type-A implementation is shown in Figure 4-8.

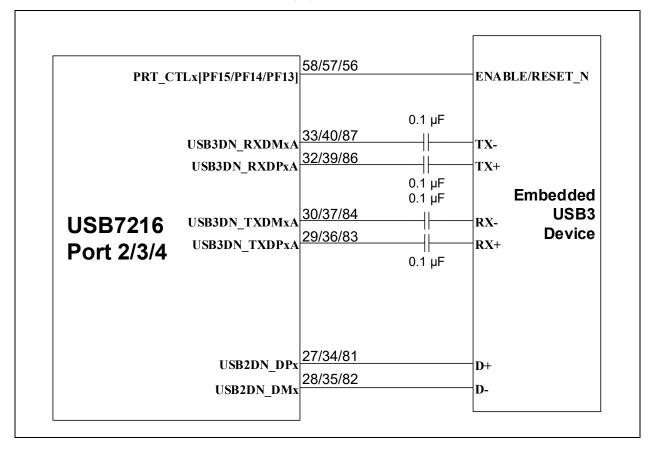
FIGURE 4-8: DOWNSTREAM PORTS 2, 3, 4 USB SIGNAL AND VBUS CONNECTIONS



4.3.3 DOWNSTREAM EMBEDDED USB3 DEVICE

For an example on how to connect downstream port 2, 3, or 4 to an embedded USB3.1 device, refer to Figure 4-9.

FIGURE 4-9: DOWNSTREAM PORTS 2, 3, 4 EMBEDDED DEVICE USB CONNECTIONS

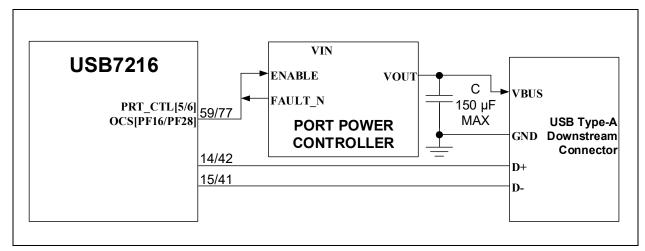


4.3.4 DOWNSTREAM PORTS 5 AND 6 VBUS AND PRT_CTL CONNECTIONS

Downstream ports 5 and 6 are basic USB2.0-only ports, and they do not include **DPx_VBUS_MON** and **DPx_DISCHARGE** pins.

A typical downstream Port 5 and 6 Type-A implementation is shown in Figure 4-10.

FIGURE 4-10: DOWNSTREAM PORTS 5 AND 6 VBUS AND PRT_CTLX CONNECTIONS



Note: The implementation as shown in Figure 4-10 assumes that the port power controller has an active-high Enable input, and an active-low, open drain style fault indicator. External polarity inversion through buffers or FETs may be required if the port power controller has different I/O characteristics.

4.4 Disabling Downstream Ports

If a downstream port of the USB7216 is unused, it should be disabled. This can be achieved through hub configuration (I^2C or OTP), or through a port disable strap option.

If using the port disable strap option, the USB_DP2 and USB_DM2 signals should be pulled high to 3.3V. This connection can be made directly to the 3.3V power net, or through a pull-up resistor. All other signals related to the associated port may be floated.

4.5 USB Protection

The use of external protection circuitry may be required to provide additional ESD protection beyond what is included in the hub IC. These generally are grouped into three categories:

- · TVS protection diodes
 - ESD protection for IEC-61000-4-2 system-level tests
- · Application-targeted protection ICs or galvanic isolation devices
 - DC overvoltage protection for short-to-battery protection
- · Common-mode chokes
 - For EMI reduction

The USB7216 can be used in conjunction with these types of devices, but these devices may have negative effect on USB signal integrity. It is important to select components accordingly and follow implementation guidelines from the device manufacturer. The following general guidelines for implementing these devices may also be followed:

- Select only devices that are designed specifically for high-speed applications. Per the USB2.0 Specification, a total of 5 pF is budgeted for connector, PCB traces, and protection circuitry. In a USB3.1 Gen 1 system, ESD protection should add no more than 0.5 pF capacitance to the differential pairs.
- Place these devices as close as possible to the USB connector.
- Never branch the USB signals to reach protection devices. Always place the protection devices directly on top of the USB differential traces.
- Always ensure a very low impedance path to a large ground plane. The effectiveness of TVS devices depends heavily on effective grounding.
- Place TVS diodes on the same layer as the USB signal trace. Avoid vias or place vias behind the TVS device if possible.

4.5.1 ADDITIONAL PROTECTION OPTIONS FOR USB3 PINS

In addition to TVS diodes, some or all of the following may be implemented:

- Use decoupling capacitors on both the TX and RX differential pairs. Decoupling capacitors on the RX pairs are not required for operation, but add some additional ESD immunity at low cost.
- Use decoupling capacitors with high voltage ratings. 0.1 μF capacitors at 0402 sizes are widely available.
- A very small resistor of 0.3-0.5W may be placed in series with the decoupling capacitor (placed physically between the TVS diode and the decoupling capacitor) to help steer more of the ESD energy through the TVS diode. A resistor network (2-resistor/4-contact) in 0402 or 0201 size can be placed with very little impact to the differential routing of the signals.

Note: Microchip PHYBoost, VariSenseTM, and High-Speed Disconnect Threshold adjustment configuration options are available for compensating the negative effects of these devices. These features can help to overcome marginal failures. It is simplest to determine the appropriate setting using lab experiments, such as USB eye diagram tests, on physical hardware.

4.6 GND and EARTH Recommendations

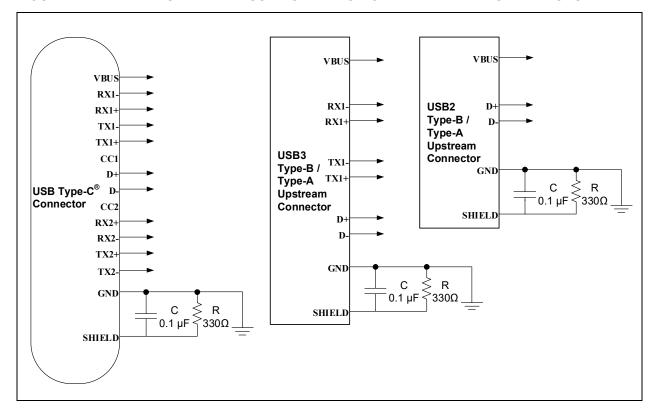
The GND pins of the USB connector must be connected to the PCB with a low impedance path directly to a large GND plane.

The EARTH pins of the USB connector may be connected in one of two ways:

- (Recommended) Connect to GND through a resistor and a capacitor in parallel. A resistor-capacitor (RC) filter can help to decouple and minimize EMI between a PCB and a USB cable.
- · Connect directly to the GND plane.

The recommended implementation is shown in Figure 4-11.

FIGURE 4-11: RECOMMENDED USB CONNECTOR GND AND EARTH CONNECTIONS



5.0 CLOCK CIRCUIT

5.1 Crystal and External Clock Connection

A 25.000 MHz (±50 ppm) reference clock is the source for the USB interface and for all other functions of the device. For exact specifications and tolerances, refer to the latest revision of the *USB7216 Data Sheet*.

- XTALI (pin 98) is the clock circuit input for the USB7216. This pin requires a capacitor to ground. One side of the
 crystal connects to this pin.
- XTALO (pin 97) is the clock circuit output for the USB7216. This pin requires a capacitor to ground. One side of the crystal connects to this pin.
- The crystal loading capacitor values are system-dependent, which are based on the total C_L spec of the crystal
 and the stray capacitance value. The PCB design, crystal, and layout all contribute to the characteristics of this circuit. A commonly used formula for calculating the appropriate physical C₁ and C₂ capacitor values is:

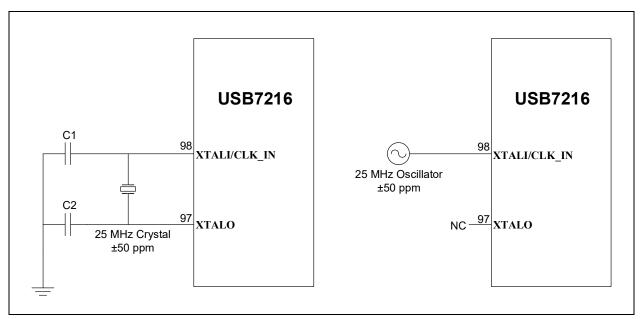
$$C_L = ((C_{X1})(C_{X2}) / (C_{X1} + C_{X2}))$$

Where, C_L is the spec from the crystal data sheet, $C_{X1} = C_{stray} + C_1$, $C_{X2} = C_{stray} + C_2$.

Note: C_{stray} is the stray or parasitic capacitance due to PCB layout. It can be assumed to be very small, in the 1-2 pF range, and then verified by physical experiments in the lab if PCB simulation tools are not available.

Alternatively, a 25.000 MHz, 3.3V clock oscillator may be used to provide the clock source for the USB7216. When
using a single-ended clock source, XTALO (pin 97) should be left floating as a No Connect (NC).

FIGURE 5-1: CRYSTAL AND OSCILLATOR CONNECTIONS



6.0 POWER AND STARTUP

6.1 RBIAS Resistor

The **RBIAS** pin on the USB7216 must connect to ground through a 12 k Ω resistor with a tolerance of 1.0%. This is used to set up critical bias currents for the internal circuitry. This should be placed as close as possible to the IC pin, and be given a dedicated, low-impedance path to a ground plane.

6.2 Board Power Supplies

6.2.1 POWER RISE TIME

The power rail voltage and rise time should adhere to the supply rise time specification as defined in the *USB7216 Data Sheet*.

If a monotonic or fast power rail rise cannot be assured, then the RESET_N signal should be controlled by a reset supervisor and only released when the power rail has reached a stable level.

6.2.2 CURRENT CAPABILITY

It is important to size the 5V and 3.3V power rails appropriately. The 5V power supply must be capable of supplying 500 mA (if BC1.2 is not enabled), 1.5A (if BC1.2 is enabled), or up to 3.0A (if the maximum Type-C current is enabled) to the USB downstream port VBUS without dropping below the minimum voltage permissible in the USB Specification.

The 3.3V and 1.15V power supply must be able to supply enough power to the USB hub IC. It is recommended that the 3.3V and 1.15V power rails be sized such that they are able to supply maximum power consumption specification as displayed in the *USB7216 Data Sheet*.

6.3 Reset Circuit

RESET_N (pin 28) is an active-low reset input. This signal resets all logic and registers within the USB7216. A hardware reset (RESET_N assertion) is not required following power-up. Refer to the latest copy of the *USB7216 Data Sheet* for reset timing requirements. Figure 6-1 shows a recommended reset circuit for powering up the USB7216 when reset is triggered by the power supply.

FIGURE 6-1: RESET TRIGGERED BY POWER SUPPLY

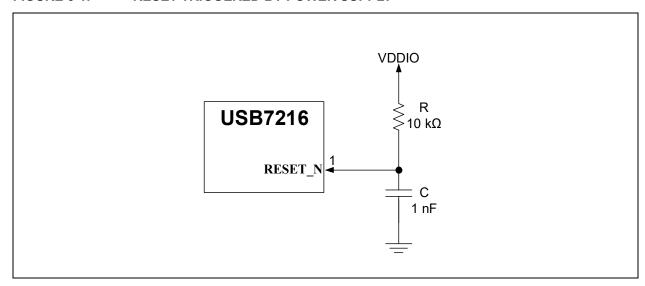
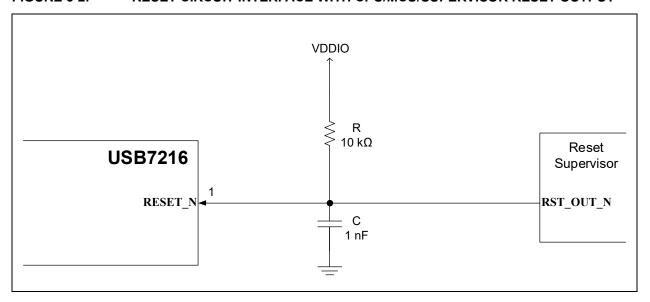


Figure 6-2 details the recommended reset circuit for applications where reset is driven by an external CPU/MCU. The reset out pin (RST_OUT_N) from the CPU/MCU provides the warm reset after power-up.

FIGURE 6-2: RESET CIRCUIT INTERFACE WITH CPU/MCU/SUPERVISOR RESET OUTPUT



7.0 EXTERNAL SPI MEMORY

7.1 SPI Operation Summary

By default, the USB7216 executes firmware from an internal read only memory (ROM). The USB7216 supports optional firmware execution from an external SPI Flash device. An SPI Flash is only required if a custom firmware is required for the application.

The SPI interface can operate at 60 MHz or 30 MHz, and can operate in Dual mode or Quad mode.

The firmware image can be executed in one of two ways:

- Execute in place: The firmware is continuously executed directly from the SPI Flash, and the interface is constantly active.
- Execute in internal SRAM: The firmware is loaded into the internal SRAM of the hub and executed internally. This
 may only be supported if the firmware image is smaller than the SRAM size of the hub.

Note:

All firmware images are developed, compiled, tested, and provided by Microchip. The SPI interface speed is an OTP-configurable option and only speeds that were specifically tested with the firmware image should be selected. The execution method is configured with the firmware image itself and cannot be changed via configuration.

7.2 Compatible SPI Flash Devices

Microchip recommends SST-brand SPI Flash devices. Microchip has verified compatibility of the following list of SPI Flash devices:

- SST26VF016B
- SST26VF032B
- SST26VF064B
- SST25VF064C
- AT25SF041
- AT26DF081

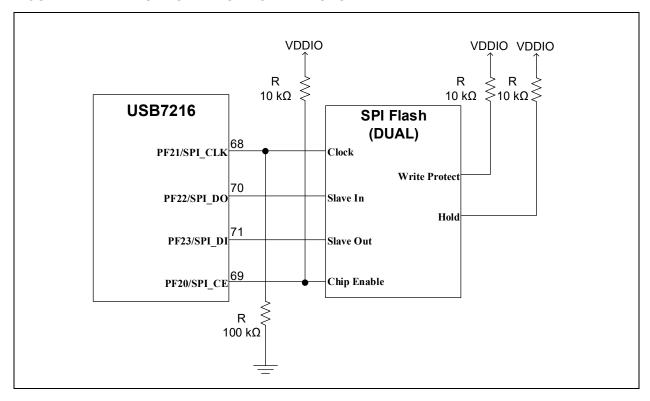
Other SPI Flash devices may be used, provided that they meet the following minimum requirements:

- · Operation at 30 MHz or 60 MHz
- Mode 0 or mode 3
- · Memory of 256 kB or larger
- Utilization of the same OpCode commands as with the above list of compatible devices
- Dual mode or Quad mode operation

7.3 SPI Connection Diagrams

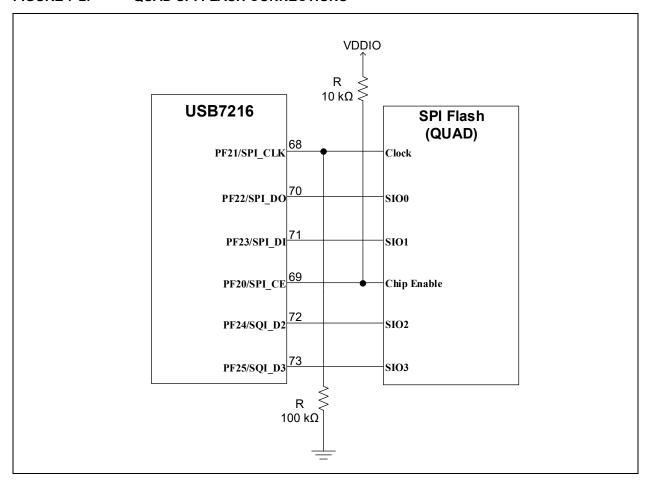
If a Dual SPI Flash device is used, the recommended schematic connections are shown in Figure 7-1.

FIGURE 7-1: DUAL SPI FLASH CONNECTIONS



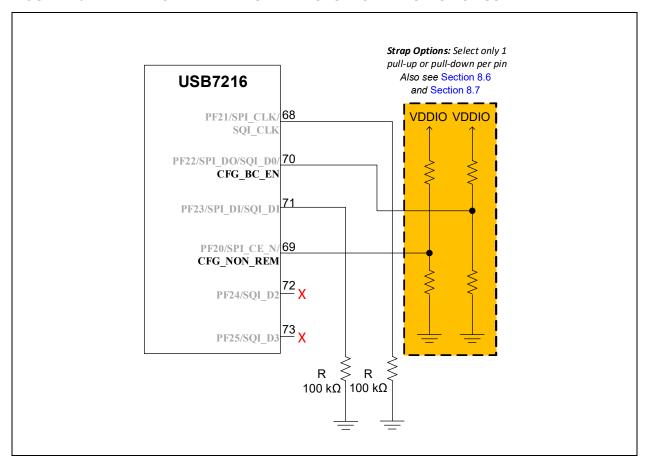
If a Quad SPI Flash device is used, the recommended schematic connections are shown in Figure 7-2.

FIGURE 7-2: QUAD SPI FLASH CONNECTIONS



If an SPI Flash device is not used, the recommended schematic connections are shown in Figure 7-3. Some of the SPI pins become configuration straps when an SPI Flash is not connected. A configuration strap option must be selected, and the pins cannot be floated.

FIGURE 7-3: RECOMMENDED CONNECTIONS IF SPI FLASH IS NOT USED



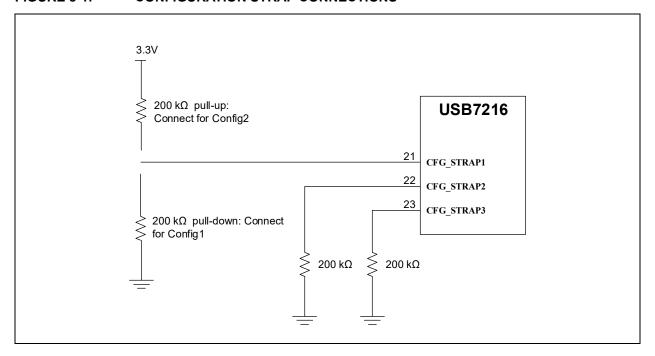
8.0 CONFIGURATION, STRAPS, AND MISCELLANEOUS INTERFACES

8.1 Configuration

There are two valid configurations for USB7216: Config1 and Config2.

Figure 8-1 shows the required Configuration pin connections for USB7216. CFG_STRAP1 can be pulled up with 200 k Ω , or it can be pulled down with 200 k Ω but no other connection is permitted.

FIGURE 8-1: CONFIGURATION STRAP CONNECTIONS



8.2 GPIOs

The GPIO pin included on USB7216 may be controlled from the USB host or from an embedded SoC/MCU. This GPIO can be used without any additional configuration. By default, all of the GPIOs are configured as inputs. If a default output power-on state is required, the default pin output state can be configured in the OTP memory of the hub or through the I^2 C/SMBus slave interface during the configuration stage (SOC_CFG). These pins are described in Table 8-1.

TABLE 8-1: AVAILABLE GPIOS

Pin	PF Pin	Name (Config1)	Name (Config2)
47	PF6	GPIO70	GPIO70
48	PF7	GPIO71	MIC_DET (I ² S)
49	PF8	GPIO72	GPIO72
50	PF9	GPIO73	GPIO73
74	PF29	GPIO93	GPIO93

Instructions for operating these pins, including register definitions, are described in full in AN2932 - USB-to-GPIO Bridging with Microchip USB72xx Hubs.

Ensure that the voltages applied to these pins are within the electrical specifications for the pins, and that any external loading is within the drive strength capabilities as described in the *USB7216 Data Sheet*.

Note: Additional GPIOs may be made available for use under certain conditions or with custom firmware development. Please consult your Microchip support representative or submit a request to the Microchip online support system to discuss options.

8.3 I²C/SMBus Connections

There are two I²C/SMBus interfaces available on USB7216. These are described in Table 8-2.

TABLE 8-2: I²C/SMBUS PINS

Pin	PF Pin	Name	Role	Configuration Requirements
2	PF30	MSTR_I2C_CLK	USB to I ² C master clock	Config1 or Config2
3	PF31	MSTR_I2C_DATA	USB to I ² C master data	Config1 or Config2
75	PF26	SLV_I2C_CLK	I ² C slave data	Config1 only
76	PF27	SLV_I2C_DATA	I ² C slave clock	Config1 only

8.3.1 SLAVE INTERFACE

The USB7216 may be configured by an embedded SoC/MCU during both the start-up and runtime stages. Pull-up resistors must be detected by the hub at start-up in order for the I²C/SMBus interface to become active. The interface command specification and configuration register set is described in full in *AN2935 - Configuration of USB7202/USB7206/USB725x*.

The Slave I²C/SMBus interface is only operational in Config1; the pins have different functions in Config2.

Typically, a pull-up resistor value of 1-10 k Ω is sufficient, depending on the interface speed and total capacitance on the I²C tree.

A pull-up voltage of 1.8V-3.3V is supported.

Note:

If $I^2C/SMBus$ pull-up resistors are detected by the USB7216 at start-up, the hub waits indefinitely to be configured by the attached $I^2C/SMBus$ master. For early prototyping, it may be necessary to physically remove the pull-up resistors until the $I^2C/SMBus$ master is fully operational and can properly configure the hub at start-up.

8.3.2 MASTER INTERFACE

The USB7216 has an I^2 C/SMBus master interface that can bridge USB commands to I^2 C/SMBus. Instructions for operating the I^2 C/SMBus master interface are contained in *AN3240 - USB-to-I2C Bridging with Microchip USB720x and USB725x Hubs*.

Typically, a pull-up resistor of 1-10 k Ω is sufficient, depending on the configured interface speed and total capacitance on the I²C tree.

A pull-up voltage of 1.8-3.3V is supported.

Ensure that all I²C/SMBus slave devices connected to the bus have unique addresses assigned.

Ensure that the USB7216 and all I²C/SMBus slave devices connected to the bus can support the target bus speed.

8.4 I²S™ Connections

There is one USB-to- l^2 S interface available on USB7216. The interface is enabled when **Config2** is selected through the CFG_STRAPx pins.

Instructions for configuring the I^2S interface, including register definitions, are described in full in AN3135 - USB to I^2S Bridging with Microchip Hubs.

A compatible I²S codec is required. By default, the I²S interface is configured to be connected to an ADAU1961.

Refer to Table 8-3 to ensure that the selected codec is compatible with the options available on USB7216.

TABLE 8-3: I²S™ CODEC COMPATIBILITY GUIDE

Parameter	Supported Values
Sampling Frequency (fs)	• 8 kHz
	• 11.025 kHz
	• 12 kHz
	• 16 kHz
	• 22.05 kHz
	• 24 kHz
	• 32 kHz
	• 44.1 kHz
	• 48 kHz
MCLK Frequency	1*fs to 1024*fs
	Since LRCLK is derived from MCLK source, the MCLK signal should be an even integer multiple of fs.
Audio Sample Size	16-bit, 24-bit, 32-bit
I ² S Audio Format	I ² S mode, Left Justified mode, Right Justified mode
I ² C Master Control Interface Frequency	100 kHz or 400 kHz
Audio Channels	Mono or Stereo
Interface Enable/Disable Options	Three Options:
	Audio OUT and Audio IN mode
	Audio OUT Only mode (Speaker Interface)
	Audio IN Only mode (Mic Interface)
Audio Jack Insertion Detection	Two Options:
	Audio Jack Insertion Detection Enabled (through HID interface)
	Audio Jack Insertion Detection Disabled

USB7216

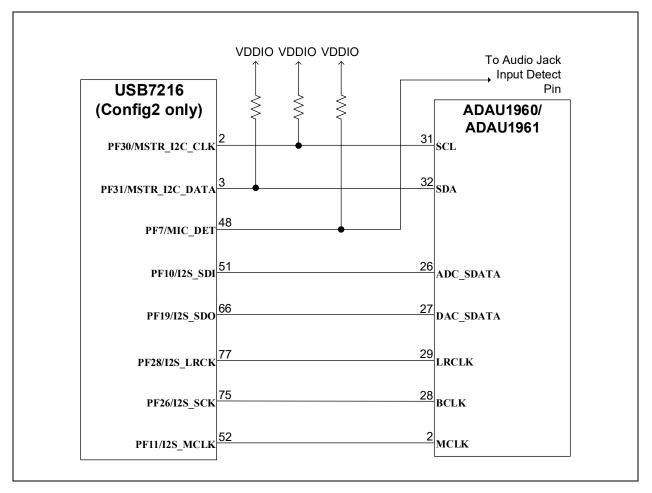
The I²S pins are described in Table 8-4.

TABLE 8-4: I²S™ PINS

Pin	PF Pin	Name	Role	Configuration Requirements
48	PF7	MIC_DET	Optional - Microphone Detection Pin	Config2
51	PF10	I2S_SDI	I ² S Serial Data In	Config2
77	PF28	I2S_LRCK	I ² S Left Right Clock	Config2
66	PF19	I2S_SDO	I ² S Serial Data Out	Config2
75	PF26	I2S_SCK	I ² S Continuous Serial Clock	Config2
52	PF11	I2S_MCLK	I ² S Master Clock	Config2

If connecting to an ADAU1961, the I^2S signals should be connected as shown in Figure 8-2. If using a different codec, consult the design guidelines provided by the manufacturer of the selected codec for implementation guidelines.

FIGURE 8-2: ADAU1961 I²S™ CODEC CONNECTIONS



8.5 Non-Removable Port Settings

In a typical USB7216 application, downstream port 1 is routed to a user-accessible USB connector. The downstream port should be configured as a removable port.

The USB7216 has a configuration strap option, CFG_NON_REM, which can be used to set the default configuration for port 1. This is located on pin 69. The strap setting is sampled once at start-up. A configuration strap option must be selected unless the hub firmware is being executed from an external SPI Flash device. These are described in Table 8-5.

TABLE 8-5: CFG NON REM

Setting	Effect
200 kΩ pull-down to GND	All ports are removable. (Recommended for most USB7216 applications)
200 kΩ pull-up to 3.3V	Port 1 is non-removable; only a valid selection if port 1 is connected directly to an embedded USB device.
10 kΩ pull-down to GND	Ports 1 and 2 are non-removable; only a valid selection if ports 1 and 2 are connected directly to embedded USB devices.
10 kΩ pull-up to 3.3V	Ports 1, 2, and 3 are non-removable; only a valid selection if ports 1, 2, and 3 are connected directly to embedded USB devices.
10Ω pull-down to GND	Ports 1, 2, 3, and 4 are non-removable; only a valid selection if ports 1, 2, 3, and 4 are connected directly to embedded USB devices.

The following guideline can be used to determine which setting to use:

- If the port is routed to a user-accessible USB connector, it is removable.
- If the port is routed to a permanently attached an embedded USB device on the same PCB, or non-user-accessible wiring or cable harness, it is **non-removable**.

Note: The removable or non-removable device settings do not impact the operation of the hub in any way. The settings only modify select USB descriptors, which the USB host may use to understand if a port is a user-accessible port or if the device is a permanently attached device. Under standard operating conditions, the USB host may or may not modify its operation based upon this information. Certain USB compliance tests are impacted by this setting, so designs that must undergo USB compliance testing and certification must ensure the configuration settings are correct.

8.6 Self-Powered/Bus-Powered Settings

In a typical USB7216 application, the hub should be configured as Self-Powered, which is the default configuration setting.

The following guidelines can be used to determine which setting to use:

- If the entire system (hub included) is powered completely from the upstream USB connector's VBUS pin and the system is designed to operate using standard USB cabling and any standard USB host, then the hub system is **bus-powered**.
- If the entire system (hub included) is always powered by a separate power connector, then the hub system is self-powered.
- If the hub included is part of a larger embedded system with fixed cabling and a fixed USB host, then the hub system is most likely self-powered (even if all of the power is derived from the upstream USB connector's VBUS pin).

Note: The self-powered or bus-powered device settings do not impact the operation of the hub in any way. The settings only modify select USB descriptors that the USB host will use to budget power accordingly. Since a standard USB2.0 port is required to supply 500 mA to the downstream port, a self-powered hub and all of its downstream ports must continue to operate within that 500 mA budget. A USB host will typically limit the downstream ports of a self-powered hub to 100 mA. Any device that connects to a self-powered hub, which declares it needs more than 100 mA will be prevented from operating by the USB host.

8.7 Battery Charging Settings

The USB7216 hub includes built-in Dedicated Charging Port (DCP), Charging Downstream Port (CDP), and vendor-specific (SE1) battery charging support.

The USB7216 has a configuration strap option, CFG_BC_EN, which can be used to set the default configuration for port 1. This is located on pin 70. The strap setting is sampled once at start-up. A configuration strap option must be selected unless the hub firmware is being executed from an external SPI Flash device. The configuration strap options are described in Table 8-6.

TABLE 8-6: CFG_BC_EN

Setting	Effect	Additional Notes
200 kΩ pull-down to GND	Port 1 BC disabled	Battery Charging is not enabled.
		Select this option if configuration will be done in hub OTP, via I ² C/SMBus, or by external firmware in SPI Flash.
		If SE1 charging is required, this strap option should be selected and SE1 must be enabled in hub OTP, via I ² C/SMBus, or by external firmware in SPI Flash.
200 kΩ pull-up to 3.3V	Port 1 BC enabled	Battery Charging is enabled.
		When no USB host is present (VBUS_DET = 0), downstream port 1 operates in Dedicated Charging Port (DCP) mode.
		When a USB host is present (VBUS_DET = 1) and the USB host has commanded the hub to enable port power, downstream port 1 operates in Charging Downstream Port (CDP) mode.
10 kΩ pull-down to GND	Port 1 and 2 BC enabled	Battery Charging is enabled.
IO GIND	enabled	When no USB host is present (VBUS_DET = 0), downstream ports 1 and 2 operate in DCP mode.
		When a USB host is present (VBUS_DET = 1) and the USB host has commanded the hub to enable port power, downstream ports 1 and 2 operate in CDP mode.
10 kΩ pull-up to 3.3V	Port 1, 2, and 3 BC enabled	Battery Charging is enabled.
3.5V	eriabled	When no USB host is present (VBUS_DET = 0), downstream ports 1, 2, and 3 operate in DCP mode.
		When a USB host is present (VBUS_DET = 1) and the USB host has commanded the hub to enable port power, downstream ports 1, 2, and 3 operate in CDP mode.
10Ω pull-down to GND	Port 1, 2, 3, and 4 BC enabled	Battery Charging is enabled.
	DO CHADICA	When no USB host is present (VBUS_DET = 0), downstream ports 1, 2, 3, and 4 operate in DCP mode.
		When a USB host is present (VBUS_DET = 1) and the USB host has commanded the hub to enable port power, downstream ports 1, 2, 3, and 4 operate in CDP mode.

Note: The vendor-specific SE1 charging mode uses the USB data lines to communicate charging capability. Hence, SE1 can only be active when no USB host is present. Additional vendor-specific charging modes exist for charging at elevated current levels when an active data connection is also present. This is handled by a vendor-specific USB protocol between the USB host and the device. The USB7216 supports these vendor-specific protocol exchanges. These vendor-specific command specifications must be obtained from the respective device vendors.

9.0

TABLE 9-1: HARDWARE DESIGN CHECKLIST

HARDWARE CHECKLIST SUMMARY

Section	Subsection	Explanation	٧	Notes
Section 2.0, "General Considerations"	Section 2.2, "Pin Check"	Verify that the pins match the data sheet.		
	Section 2.3, "Ground"	Verify that the ground nets are connected.		
	Section 2.4, "USB-IF Compliant USB Connectors"	Verify that USB-IF-compliant USB connectors with an assigned TID are used in the design (if USB compliance is required for the design).		
Section 3.0, "Power and Bypass Capacitance"	Section 3.0, "Power and Bypass Capacitance"	 Ensure VDD33 is in the range 3.0V to 3.6V, and a 0.1 µF capacitor is on each pin. Ensure VCORE is in the range 1.09V to 1.21V, and a 0.1 µF capacitor is on each pin. 		
Section 4.0, "USB Signals and Connections"	Section 4.1, "Upstream Port USB Signals"	Verify that the USB data pins are correctly routed to the USB connectors. Pay special attention to the polarity of the USB2.0 D+ and D-data lines, and do not cross the USB3 TX and RX differential pairs. Verify that the upstream port VBUS has no more than 10 uF capacitance and that the VBUS signal is properly divided down to a 3.3V signal and connected to the VBUS_DET pin of the hub.		
	Section 4.2, "Downstream Port 1"	Verify that the USB data pins are correctly routed to the USB connectors. Pay special attention to the polarity of the USB2.0 D+ and D-data lines, and do not cross the USB3 TX and RX differential pairs. Verify that PRT_CTL1 is properly connected to both the Enable pin of the downstream port power controller and the fault indicator output of the port power controller. Ensure the port power controller current capability is sized appropriately (500 mA, 900 mA, 1.5A, or 3A) and that the overcurrent threshold is set appropriately.		
	Section 4.3, "Downstream Ports 2-6"	Verify that the USB data pins are correctly routed to the USB connectors. Pay special attention to the polarity of the USB2.0 D+ and D-data lines, and do not cross the USB3 TX and RX differential pairs. Verify that PRT_CTLx signals are properly connected to both the Enable pins of the downstream port power controllers and the fault indicator outputs of the port power controller. Ensure the port power controller current capability is sized appropriately (500 mA, 900 mA, 1.5A, or 3A) and that the overcurrent threshold is set appropriately.		
	Section 4.4, "Disabling Downstream Ports"	If any of the USB ports are unused, ensure they are properly disabled via pin strap. If pin strapping is not used, other methods may be used such as I ² C/SMBus configuration or OTP configuration.		
	Section 4.5, "USB Protection"	Verify that ESD/EMI protection devices are designed specifically for high-speed data applications and that the combined parasitic capacitance of the protection devices, USB traces, and USB connector do not exceed 5 pF on each USB2 trace. Protection devices on USB3 traces should not add more than 0.5 pF on each line.		

TABLE 9-1: HARDWARE DESIGN CHECKLIST (CONTINUED)

Section	Subsection	Explanation	٧	Notes
	Section 4.6, "GND and EARTH Recommendations"	Verify that the USB connector is properly connected to PCB ground on both the GND pins and the SHIELD pins. It is recommended that an RC filter be placed in between the SHIELD pins and PCB ground.		
Section 5.0, "Clock Circuit"	Section 5.1, "Crystal and External Clock Connection"	Confirm the crystal or clock is 25.000 MHz (±50 ppm). If a single-ended external clock source is used instead of the crystal oscillator, ensure that it is connected to XTALI while leaving XTALO floating. If a crystal is used, ensure the loading capacitors are appropriately		
Section 6.0, "Power and	Section 6.1, "RBIAS Resistor"	sized for the crystal loading requirement. A parallel resistor is not required. Confirm that a 12.0 k Ω 1% resistor is connected between the RBIAS		
Startup"	Society C.1, Tibir C Trooper	pin and the PCB ground.		
	Section 6.2, "Board Power Supplies"	Verify that the board power supplies deliver 3.0-3.6V to VDD33 and 1.09V-1.21V to VCORE, and that the power-on rise time meets the requirement of the hub as defined in the data sheet. If the rise time requirement cannot be met, ensure that the RESET_N line is held low until the power regulators reach a steady state.		
	Section 6.3, "Reset Circuit"	Ensure that the RESET_N signal has an external pull-up resistor, or is otherwise properly controlled by an external SoC, MCU, or Reset supervisor device.		
Section 7.0, "External SPI Memory"	Section 7.1, "SPI Operation Summary"	Determine if a custom SPI firmware image is required and which mode of operation the selected SPI Flash device must support.		
	Section 7.2, "Compatible SPI Flash Devices"	Ensure the selected SPI Flash device is compatible with the hub.		
	Section 7.3, "SPI Connection Diagrams"	Verify that the SPI Flash is connected according to the diagrams in Figure 7-1 or Figure 7-2. Follow Figure 7-3 if no SPI Flash is connected in the design.		
Section 8.0, "Configuration, Straps, and Miscellaneous Interfaces"	Section 8.1, "Configuration"	Verify that the 3 CFG_STRAP pins are connected according to Figure 8-1.		

	TABLE 9-1:	HARDWARE DESIGN CHECKLIST	(CONTINUED)
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Section	Subsection	Explanation	٧	Notes
	Section 8.2, "GPIOs"	Verify that any GPIO pins that will be used as GPIOs within the application are connected properly, and never exceed the voltage maximums/minimums, or overload the current source/sink maximums as defined in the hub data sheet.		
	Section 8.3, "I2C/SMBus Connections"	If the USB-to-I ² C/SMBus slave interface is implemented, ensure that appropriate pull-up resistors are connected and that the connections to the I ² C/SMBus master are correct. To use the Slave I ² C/SMBus interface, Config1 must have been selected. Note that the pull-up resistors are detected on the I ² C/SMBus slave interface, the USB hub will not enumerate to a USB host until it receives the special "Attach" command from the I ² C/SMBus master.		
	Section 8.4, "I2S™ Connections"	If using the USB-to-l ² S bridge feature, ensure that Config2 is selected via the CFG_STRAP pin, and ensure that the pin connections to the l ² S codec are correct. If using any codec other that the ADAU1961, ensure that it is compatible by referencing the compatibility guide in Table 8-1.		
	Section 8.5, "Non-Removable Port Settings"	Verify that the CFG_NON_REM configuration strap is set per application requirements. Most USB7216 applications should set this strap to the 'Port 1 Removable' setting.		
	Section 8.6, "Self-Powered/Bus-Powered Settings"	Verify the application requirements for Self-Powered or Bus-Powered operation. If Self-Powered operation is required, then no additional configuration or circuitry is required. If Bus-Powered operation is required, then the hub must be configured via OTP or I ² C/SMBus.		
	Section 8.7, "Battery Charging Settings"	Verify that the CFG_BC_EN configuration strap is set per application requirements. Most USB7216 applications should set this strap to the 'Port 1 BC Enable' setting.		

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APPENDIX A: REVISION HISTORY

TABLE A-1: REVISION HISTORY

Revision Level & Date	Section/Figure/Entry	Correction
DS00003286A (10-28-19)	Initial release	

THE MICROCHIP WEB SITE

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NOTES:

Note the following details of the code protection feature on Microchip devices:

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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